

Amendments to the Claims

In The Claims:

Please amend the claims as follows:

1. (Twice Amended) A method for plating a second metal directly to a first metal, said method comprising [the steps of]:

providing a semiconductor substrate including at least one metal feature and at least one insulating layer covering said metal feature and said substrate;

forming at least one recess in said at least one insulating layer thereby exposing at least a portion of said metal feature;

forming at least one conductive barrier layer over said insulating layer and said exposed portion of said metal feature;

forming a plating seed layer of a first metal over said at least one barrier layer;

depositing a photoresist layer over [aid] said plating seed layer and in said at least one recess;

removing portions of said photoresist layer and portions of said plating seed layer outside of said at least one recess;

removing photoresist remaining in said at least one recess; and

electroplating a second metal to said plating seed layer in said recess without utilizing a lithographic mask.

24. (Twice Amended) A method for plating a second metal directly to a first metal. said method comprising:

providing a semiconductor substrate including at least one metal feature and at least one insulating layer covering said metal feature and said substrate;

forming at least one recess in said at least one insulating layer thereby exposing at least a portion of said metal feature;

forming at least one conductive barrier layer over said insulating layer and said exposed portion of said metal feature;

forming a plating seed layer of a first metal over said at least one barrier layer;

removing portions of said plating seed layer outside of said at least one recess;

and

electroplating a second metal to said plating seed layer in said recess without utilizing a lithographic mask.

30. (Twice Amended) The method according to Claim 29, wherein said copper is sputter coated on said conductive barrier layer.

38. (Twice Amended) The method according to Claim 24, further comprising:
removing said at least one conductive barrier layer from horizontal
portions between said at least one recess.

49. (Twice Amended) The method according to Claim 48, wherein said copper is sputter coated on said conductive barrier layer.

57. (Twice Amended) The method according to Claim 22, further comprising the step of:

removing said at least one conductive barrier layer from horizontal
portions between said at least one recess.